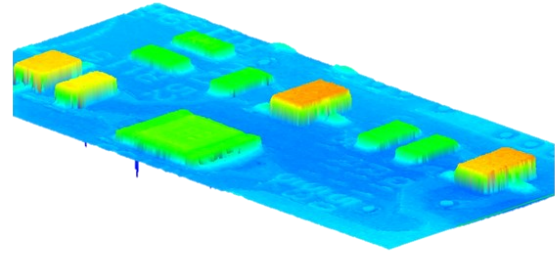
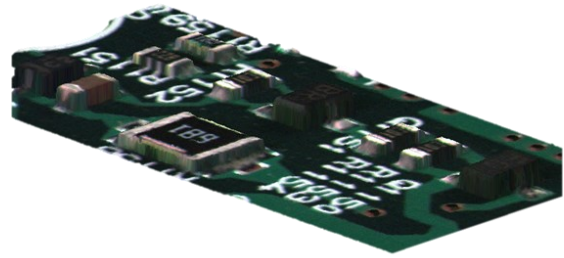


4ISOt



3D Topographical Imaging AOI

✓ Automatic Full profile 2D and 3D AOI

✓ 2D and 3D simultaneous inspection (using patented sensor technology)

✓ Flexible Close to vertical dual (front & rear), high energy lasers

✓ High speed 12M (4096 x 3072) CMOS capturing sensor with optical fiber interface

✓ High end RGB LED light dome

✓ High vibration resistance 1/4000 Sec shutter speed

✓ Telecentric 18/9um (normal speed scan/high resolution scan) standard lens resolution. Optional 12/6um lens resolution

✓ Z-Axis for warp compensation

✓ Offline Programming/Debug Station

✓ Massive 30 mm component height measurement

100% 3D inspection of PCBA .

Full colour 3D inspection coverage Powerful inspection algorithms .

Shadow and blind spot reduction. Short wavelength Laser for high Z pixel quality.

State of the art image capture, High speed interface.

Superior image quality and analysis.

Not effected by vibrations from other production processes.

Switchable resolution 18 or 9 um on the fly. High resolution capable of 0201 as standard or optionally Super High resolution 12/6um for 03015 and 008004.

Dynamic compensation of PCB warp, for accurate height measurement.

Reliable offline programming, Minimal line down time.

Unrivaled range of height measurement.



because inspection matters

Specifications	ISO Spector SL330	ISO Spector SL510
Maximum PCB Size	330x250mm (13.8" x 9.8")	510x460mm (20.1" x 18.1")
Characteristics		
Product type	Topographical 3D Automatic optical inspection and measurement	
In-line	Inline SMEMA 2.0	
Movement type	Camera X,Y,Z	
PCB movement	Stationary	
PCB fixation	Top Clamping, Pin based PCB support	
Parts inspection	Presence, Polarity, Offset, OCV, Soldering	
3D capture	Short wavelength (Blue/Violet) high angle Lasers	
2D capture	RGB high intensity LED	
Camera type	12MP (4096 x 3072) Fibre interface	
Camera Field Of View/Resolution	74mm wide 18/9µm, Optional 49 mm 12/6µm	
Lens	High Resolution custom Telecentric	
Lighting system	Triple LED rings: Red, Green, Blue	
Specifications		
Minimum inspection component size	0201" (18/9µm resolution) 008004" (12/6µm resolution)	
Positioning accuracy	Enclosed glass scales ±10µm X,Y,Z	
Component clearance (top)	+40mm (1.6")	
Component clearance (bottom)	-36mm (-1.4") With backup pins -40mm (1.6") without	
Minimum PCB Size	50x50mm (1.9" x 1.9")	
Warp compensation	±2 mm (± 0.080")	
Z axis stroke	56mm Range +48mm -8mm (2.2" Range +1.9" -0.3")	
Inspection capacity typical	18µm 3600mm ² sec High speed. 9µm 1800mm ² sec High Resolution.	
Power	100-240 Vac / 1.5 kVa single phase	
Interfacing		
Control PC type (not included)	Dell Workstation Windows 8.1 Pro	
Control interface	Custom control card	
Data interface	Fibre optic GigE Vision	
General		
Operating temperature	15-35°C (60-95 F)	
Operating humidity	15-85 % RH	
External size	W1000x D1000 x H2000 mm (39.4" x 39.4" x 77.8")	W1400x D1300 x H2000 mm (55.1" x 51.2" x 77.8")
Weight	400kg (882lbs)	550kg (1212lbs)

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